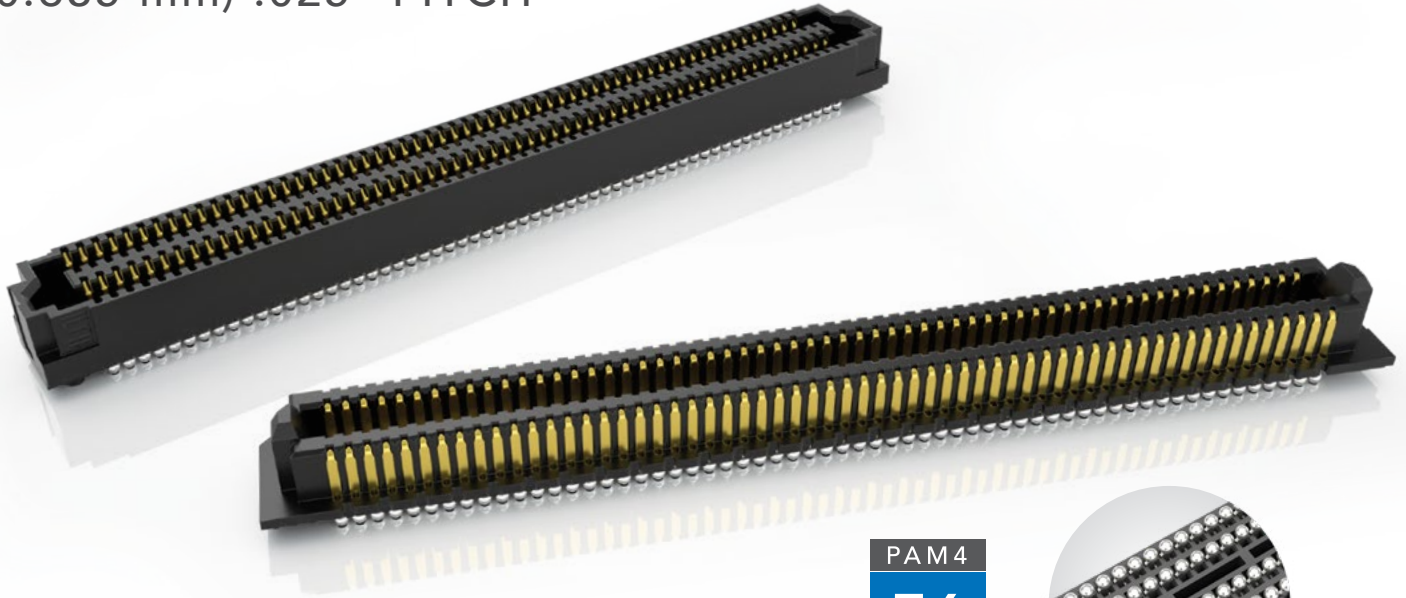


ACCELERATE[®] HD

HIGH-DENSITY SLIM BODY ARRAYS

(0.635 mm) .025" PITCH



FEATURES & BENEFITS

- Up to 240 positions in 4-row design (400 positions in development)
- Low-profile 5 mm stack heights
- Slim 5 mm width body design
- Edge Rate[®] contact system optimized for signal integrity performance
- Open-pin-field for grounding and routing flexibility
- Right-angle (ADF6-RA) and other stack heights in development
- PCIe[®] 5.0 capable
- Compatible with mPower[®] (UMPT/UMPS) for a power signal solution

PAM 4
56
G b p s



Solder ball technology
for simplified processing

HIGHER DENSITY THAN PREVIOUS GENERATION STRIPS



Actual Size Shown
(68.22 mm x 5.00 mm)

ADM6/ADF6 Series (400 total positions)

KEY SPECIFICATIONS

PITCH	TOTAL POSITIONS	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	OPERATING TEMP RANGE	CURRENT RATING	WORKING VOLTAGE	LEAD-FREE SOLDERABLE
(0.635 mm) .025"	40 - 240	Black LCP	Copper Alloy	Au or Sn over 50 μ" (1.27 μm) Ni	-55 °C to +125 °C	1.34 A per pin (4 pins powered)	Testing now	Yes

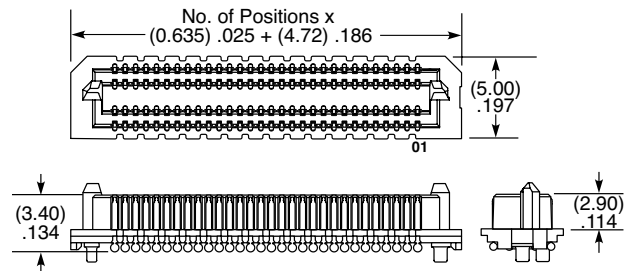
(0.635 mm) .025" PITCH • SLIM BODY OPEN-PIN-FIELD ARRAYS

SERIES	NO. OF POSITIONS	LEAD STYLE	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	OPTION	"X" R
ADM6 Terminal	-10, -20, -30, -40, -50, -60 (per row)	-01.5 = 1.5 mm (ADM6 only)	-L = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on tail	-4 = Four Rows	-2 = Lead-Free Solder Ball	(Leave blank for no alignment pin) -A = Alignment Pin	-TR = Tape & Reel -FR = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)
ADF6 Socket		-03.5 = 3.5 mm (ADF6 only)					

ADM6

Board Mates:
ADF6

Standoffs:
JSO



View complete specifications at: samtec.com?ADM6

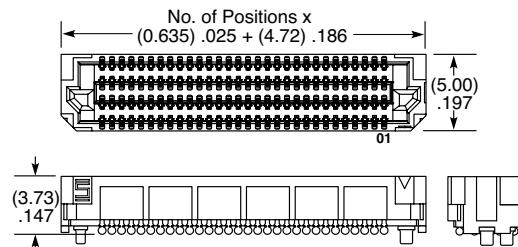
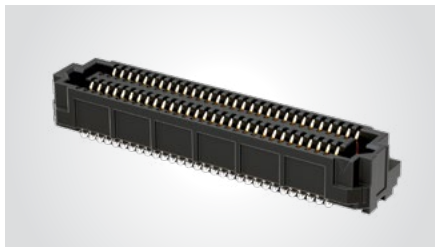
MATED HEIGHTS *	
ADF6 LEAD STYLE	ADM6 LEAD STYLE
-01.5	-01.5
-03.5	(5 mm) .197"

* Processing conditions will affect mated height.

ADF6

Board Mates:
ADM6

Standoffs:
JSO



Notes:

Some sizes, styles and options are non-standard, non-returnable

View complete specifications at: samtec.com?ADF6